The **T-3002-FC3** series is Tresky’s most flexible die bonding platform. The systems can run all basic functions as well as the industries most advanced applications by adding a wide range of available options. As with all of Tresky’s products, the FC3 incorporates True Vertical Technology™ which guarantees parallelism between chip and substrate at any bond height. Together with superior ergonomics the FC3 platform is the industry’s most sophisticated system in its class. The **T-3002-FC3** is equipped with Tresky’s die ejector system for pick-up from wafer.
Advanced multi functional die bonder with superior ergonomic design and programmable, high accuracy Z-Drive and bonding force control.

APPLICATIONS:
Die Attach, Die Sorting, Flip-Chip, 3D Packaging, MEMS, MOEMS, VCSEL, Photonics, Ultrasonic, Thermosonic, RFID, Sensor Assembly, Adhesive Bonding, Eutectic Bonding (AuAu, AuSn, ......) ......

FEATURES AND OPTIONS:
- Interface for temperature profile and video imaging
- Programmable Z-Drive with Bonding Force Control
- TRUE VERTICAL TECHNOLOGY™
  Z-movement 95mm with 360° Tool rotation; Dispenser, Stamping, Ultrasonic, Scrub, Tool Heating, Pre Form Spindle, ...
- XY placement stage supporting:
  Waffle/Gel - Pack -, Substrate - Holder, various Heating Plates

TECHNICAL DATA:
XY- Movement (placement stage): 220mm x 220mm (manual)
XY- Movement (wafer stage): 220mm x 220mm (manual)
Z- Movement: 95mm (automatic)
Spindle Rotation: 360°
Bond Force (standard range): 20g - 400g (other force ranges available)
Bond Force (repeatability): ±1g
Z-Measurement resolution: ±0.001mm
Max. PC Board-/ Substrate Size: 400mm x 280mm
Placement accuracy: ±10µm; ±2µm optional (process depending)
Connections: Compressed air 5 - 6 bar / Vacuum 0.6 bar (abs)
Dimensions: 900mm x 800mm x 700mm
Weight: 85kg
Voltage: 110V / 220V

HEADQUATERS

www.tresky.com